

App. No. 10/709,889  
Amendment dated November 23, 2005  
Reply to Office action of August 23, 2005

**Amendments to the Specification (other than claims):**

Please replace paragraph [0018] with the following amended paragraph:

[0018] Ceramic-and-metal composites (ceramic-metal composites hereinafter) have high thermal conductivities; moreover their Young's moduli are higher than that of metals, and their toughness is greater than that of ceramics. Accordingly, rendering a ceramic-metal composite into a holder 1 for semiconductor or liquid-crystal manufacturing devices facilitates achieving temperature uniformity in the retaining face 4 of the holder 1 (Figs. 1A and 1B), and makes the holder unlikely to break even in situations in which localized heat stress is put on the holder. Nevertheless, owing to the electroconductivity of ceramic-metal composites, a conductive layer cannot be formed directly onto a ceramic-metal composite.